



PTO/SS/08A (10-01)
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Substitute for form 1449A/PTO		Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Application Number	09/653,411
		Filing Date	August 31, 2000
		First Named Inventor	Whonchee Lee
		Art Unit	2815
		Examiner Name	Joseph H. Nguyen
Sheet 1 of 3	Attorney Docket Number	M4065.0361/P361	

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Examiner Initials*	Class No.	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			
JN	AA	2001/0036746	11-01-2001	Sato et al.	
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Substitute for form 1448A/PTO		Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Application Number	09/653,411
		Filing Date	August 31, 2000
		First Named Inventor	Whonchee Lee
		Art Unit	2815
		Examiner Name	Joseph H. Nguyen
Sheet 2 of 3	Attorney Docket Number	M4065.0381/P381	

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¹ Applicant's unique citation designation number (optional). ² See attached Kind Codes of USPTO Patent Documents at www.uspto.gov or MPEP 601.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the application number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 18 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

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Substitute for form 1449B/PTO		Complete if Known			
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Application Number	09/653,411		
		Filing Date	August 31, 2000		
		First Named Inventor	Whonchee Lee		
		Group Art Unit	2815		
		Examiner Name	Joseph H. Nguyen		
Sheet	3	of	3	Attorney Docket Number	M4065.0361/P361

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Examiner Signature	JOSEPH H. NGUYEN	Date Considered	11/10/04
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

*Applicant's unique citation designation number (optional). *Applicant is to place a check mark here if English language Translation is attached.

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